1:2 Fanout Differential LVPECL to LVTTL Translator

The MC100EPT26 is a 1:2 Fanout Differential LVPECL to LVTTL translator. Because LVPECL (Positive ECL) levels are used only +3.3V and ground are required. The small outline 8-lead SOIC package and the 1:2 fanout design of the EPT26 makes it ideal for applications which require the low skew duplication of a signal in a tightly packed PC board.

The VBB output allows the EPT26 to be used in a <u>single</u>-ended input mode. In this mode the VBB output is tied to the $\overline{D0}$ input for a non-inverting buffer or the D0 input for an inverting buffer. If used, the VBB pin should be bypassed to ground via a $0.01\mu F$ capacitator.

- 1.4ns Typical Propagation Delay
- 275MHz Fmax (Clock bit stream, not pseudo-random)
- Differential LVPECL inputs
- Small Outline SOIC Package
- 24mA TTL outputs
- Flowthrough Pinouts
- ESD Protection: >2KV HBM, >100V MM
- Internal Input Resistors: Pulldown on D, Pulldown and Pullup on \overline{D}
- Q Outputs will default LOW with inputs open or at VEE.
- VBB Output
- New Differential Input Common Mode Range
- Moisture Sensitivity Level 1, Indefinite Time Out of Drypack.
 For Additional Information, See Application Note AND8003/D
- Flammability Rating: UL-94 code V-0 @ 1/8", Oxygen Index 28 to 34
- Transistor Count = 117 devices

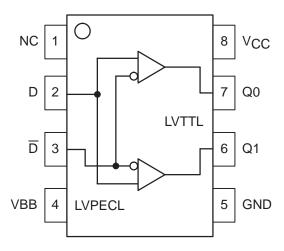


Figure 1. 8-Lead Pinout (Top View) and Logic Diagram



http://onsemi.com

MARKING DIAGRAMS*



SO-8 D SUFFIX CASE 751





TSSOP-8 DT SUFFIX CASE 948R



A = Assembly Location

L = Wafer Lot

Y = Year

W = Work Week

*For additional information, see Application Note AND8002/D

PIN DESCRIPTION				
PIN FUNCTION				
Q0, Q1	LVTTL Outputs			
D, \overline{D}	Differential LVPECL Input Pair			
VCC	Positive Supply			
V _{BB} Reference Voltage				
GND	Ground			

ORDERING INFORMATION

Device	Package	Shipping		
MC100EPT26D	SO-8	98 Units / Rail		
MC100EPT26DR2	SO-8	2500 / Reel		
MC100EPT26DT	TSSOP-8	98 Units / Rail		
MC100EPT26DTR2	TSSOP-8	2500 / Reel		

MAXIMUM RATINGS*

Symbol	Parameter		Value	Unit
V _{CC}	Power Supply (GND = 0V)		0 to 3.8	VDC
VI	Input Voltage (GND = 0V, V _I not more positive th	an V _{CC})	0 to 3.8	VDC
l _{out}	Output Current	Continuous Surge	50 100	mA
I _{BB}	V _{BB} Sink/Source Current†		± 0.5	mA
TA	Operating Temperature Range		-40 to +85	°C
T _{stg}	Storage Temperature		-65 to +150	°C
θЈΑ	Thermal Resistance (Junction-to-Ambient)	Still Air 500lfpm	190 130	°C/W
θJC	Thermal Resistance (Junction-to-Case)		41 to 44 ± 5%	°C/W
T _{sol}	Solder Temperature (<2 to 3 Seconds: 245°C des	sired)	265	°C

^{*} Maximum Ratings are those values beyond which damage to the device may occur.

DC CHARACTERISTICS (VCC = $3.3V \pm 0.3V$; GND = 0V; TA = $-40^{\circ}C$ to $85^{\circ}C$)

Symbol	Characteristic	Min	Тур	Max	Unit	
ICCH	Power Supply Current (Outputs set to HIGH)		10	20	18	mA
ICCL	Power Supply Current (Outputs set to LOW)		15	28	35	mA
VIH	Input HIGH Voltage (V _{CC} = 3.3) (Note 1.)		2135		2420	mV
VIL	Input LOW Voltage (V _{CC} = 3.3) (Note 1.)		1490		1825	mV
lН	Input HIGH Current				150	μΑ
IIL	Input LOW Current	<u>)</u>	-150		0.5	μА
Vон	Output HIGH Voltage (I _{OH} = -3.0mA) (Note 2.)		2.4			V
VOL	Output LOW Voltage (I _{OL} = 24mA) (Note 2.)				0.5	V
los	Output Short Circuit Current		- 50		-150	mA
VIHCMR	Input HIGH Voltage Common Mode Range (Note 3.)		2.0		3.3	V
V _{BB}	Output Voltage Reference			2.0		V

NOTE: 100EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

- All values vary 1:1 with V_{CC}.
 All loading with 500 ohms to GND, CL = 20pF.
 V_{IHCMR} min varies 1:1 with GND, max varies 1:1 with V_{CC}.

AC CHARACTERISTICS ($V_{CC} = 3.3V \pm 0.3V$; GND = 0V)

			–40°C		25°C			85°C				
Symbol	Characteristic		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency (Note 4.)		275	350		275	350		275	350		MHz
tPLH, tPHL	Propagation Delay to Output Differential (Note 5.)		1.2 1.2	1.5 1.5	1.8 1.8	1.2 1.2	1.5 1.5	1.8 1.8	1.3 1.2	1.7 1.5	2.2 1.8	ns
tSK+ + tSK tSKPP	Output-to-Output Skew++ Output-to-Output Skew Part-to-Part Skew (Note 6.)			60 25 500			60 25 500			60 25 500		ps
^t JITTER	Cycle-to-Cycle Jitter			TBD			TBD			TBD		ps
VPP	Input Voltage Swing (Diff.)		150	800	1200	150	800	1200	150	800	1200	mV
t _r t _f	Output Rise/Fall Times (0.8V – 2.0V)	Q, Q	330	600	900	330	600	900	330	650	900	ps

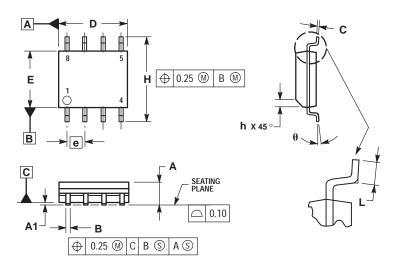
^{4.} F_{max} guaranteed for functionality only. V_{OL} and V_{OH} levels are guaranteed at DC only. 5. Reference ($V_{CC} = 3.3V \pm 5\%$, GND = 0V)

[†] Use for inputs of same package only.

^{6.} Skews are measured between outputs under identical transitions.

PACKAGE DIMENSIONS

SO-8 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751-06 ISSUE T



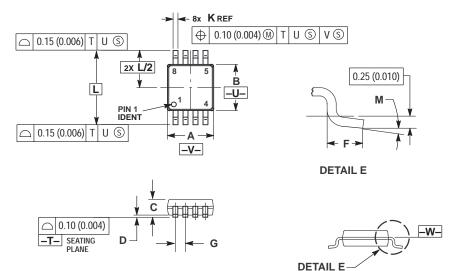
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. DIMENSIONS ARE IN MILLIMETER.
 3. DIMENSION D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS					
DIM	MIN	MAX				
Α	1.35	1.75				
A1	0.10	0.25				
В	0.35	0.49				
С	0.19	0.25				
D	4.80	5.00				
Ε	3.80	4.00				
е	1.27	1.27 BSC				
Н	5.80	6.20				
h	0.25	0.50				
L	0.40	1.25				
θ	0 °	7 °				

PACKAGE DIMENSIONS

TSSOP-8 DT SUFFIX

PLASTIC TSSOP PACKAGE CASE 948R-02 ISSUE A



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD
- J. DIMENSION A DUES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 J. DIMENSION B DOES NOT INCLUDE
- IDMENSION BOVES NOT INCLUDE
 INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL NOT
 EXCEED 0.25 (0.010) PER SIDE.

 TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE
 DETERMINED AT DATUM PLANE -W-

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.114	0.122	
В	2.90	3.10	0.114	0.122	
С	0.80	1.10	0.031	0.043	
D	0.05	0.15	0.002	0.006	
F	0.40	0.70	0.016	0.028	
G	0.65	BSC	0.026 BSC		
K	0.25	0.40	0.010	0.016	
L	4.90	BSC	0.193	BSC	
M	0°	6 °	0°	6°	

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